

**FIG.1B**

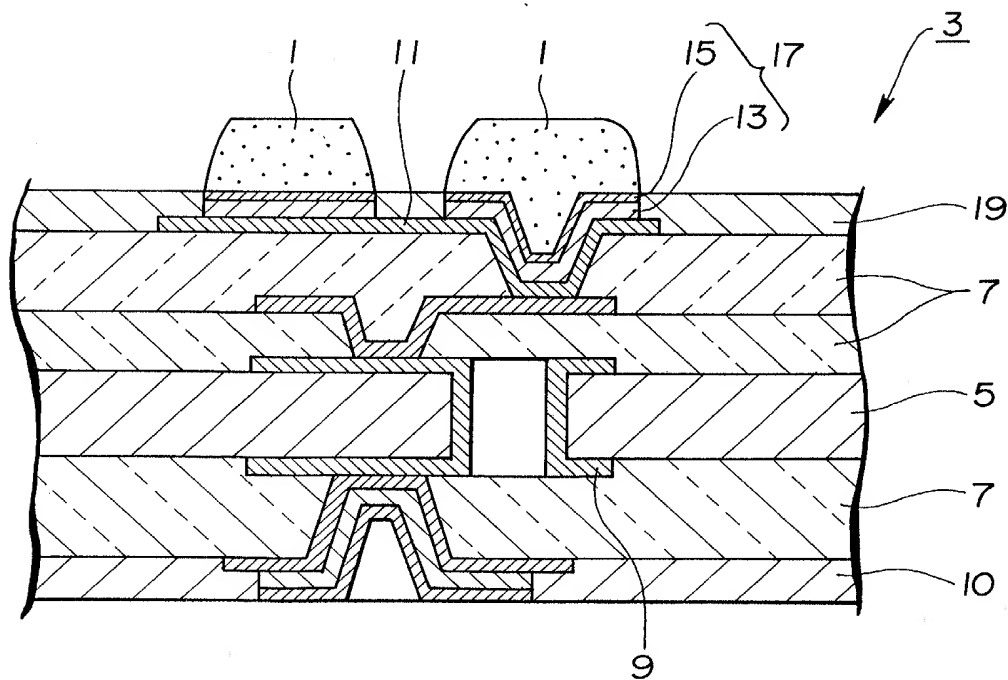
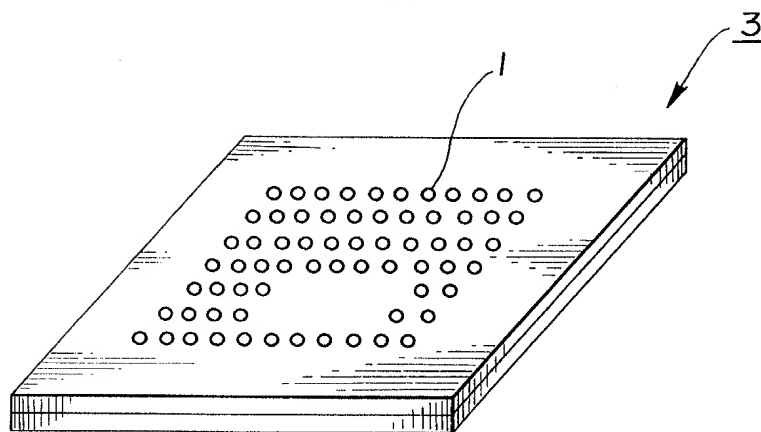


FIG.2A

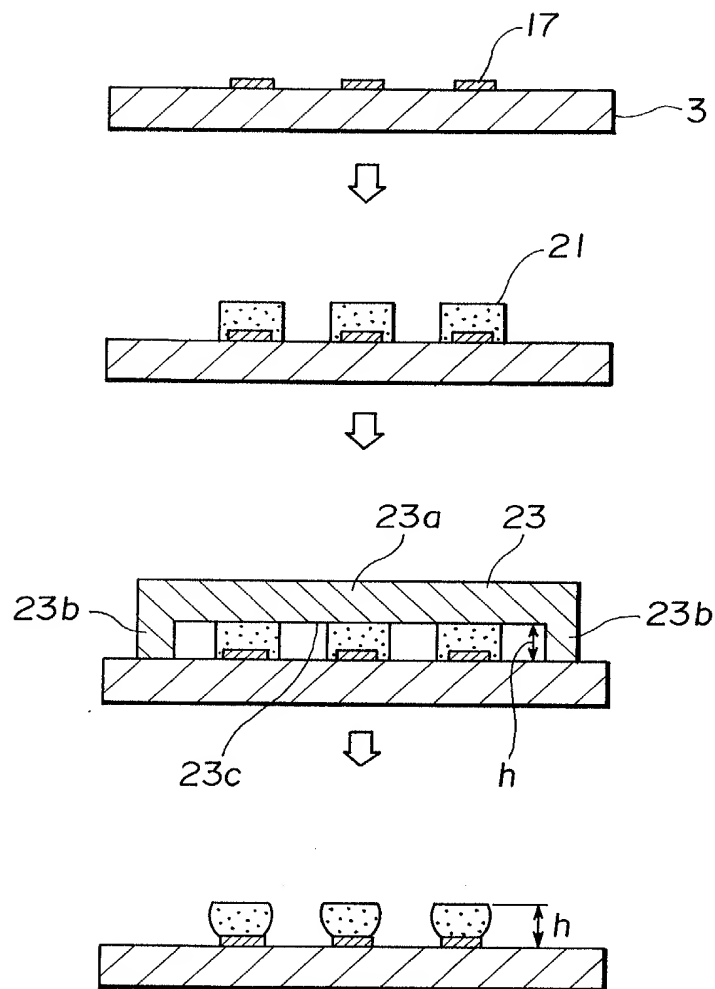


FIG.2B

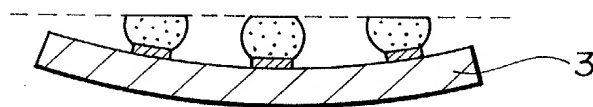
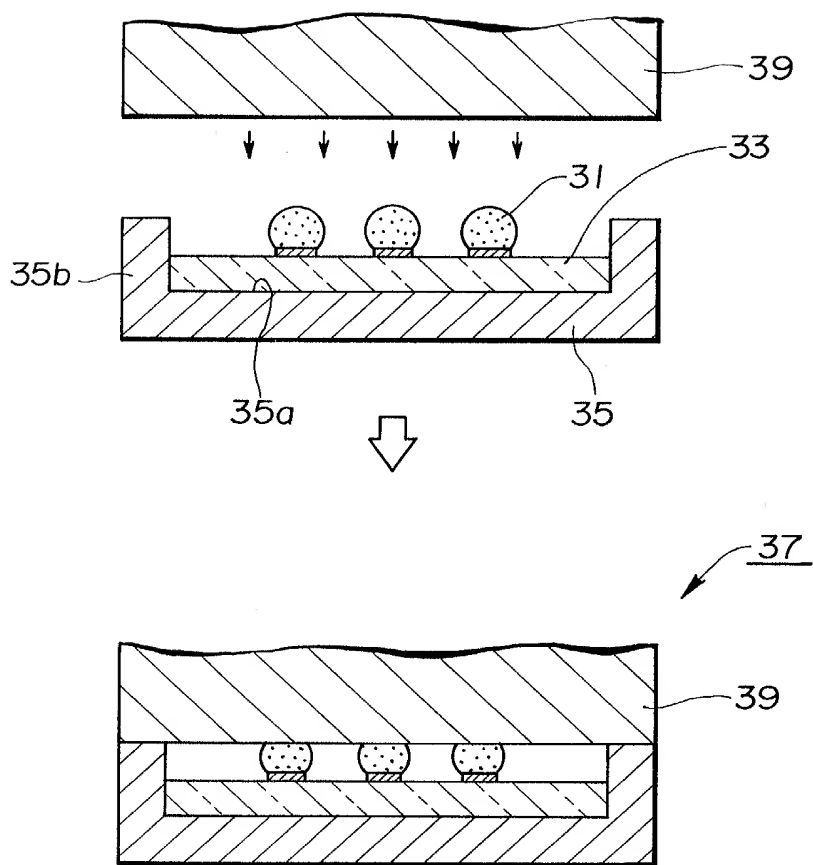
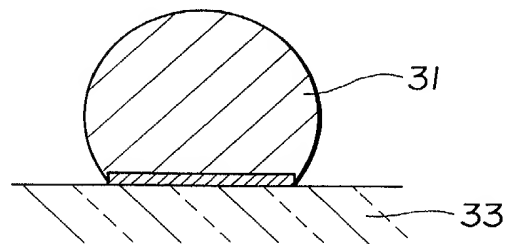


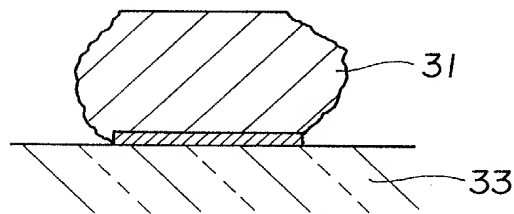
FIG.3



**FIG.4A**



**FIG.4B**



**FIG.4C**

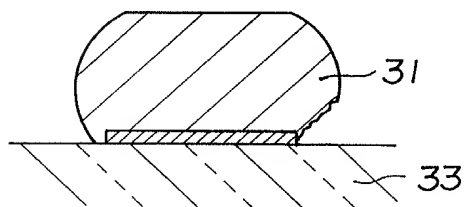


FIG.5

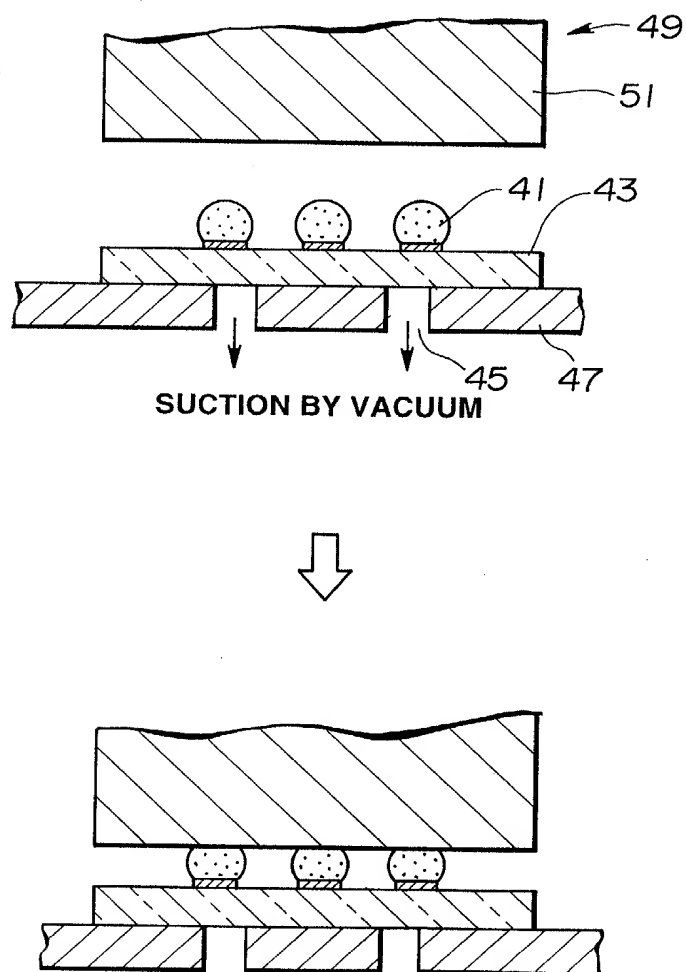


FIG.6

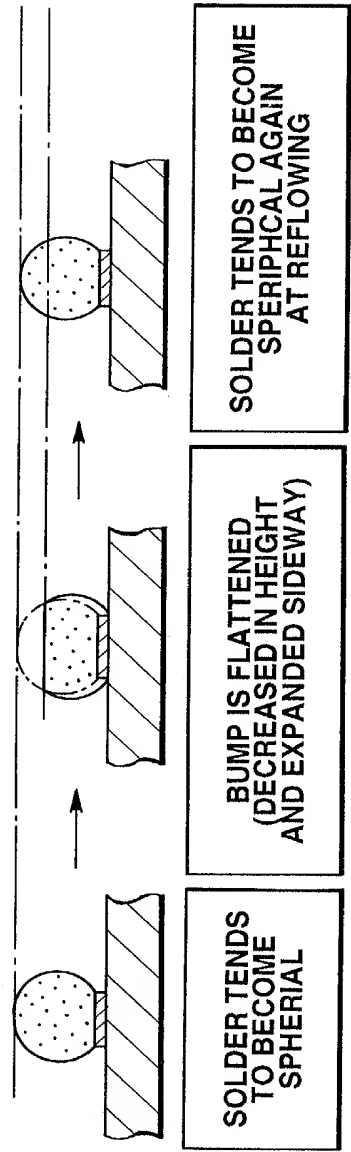


FIG.7

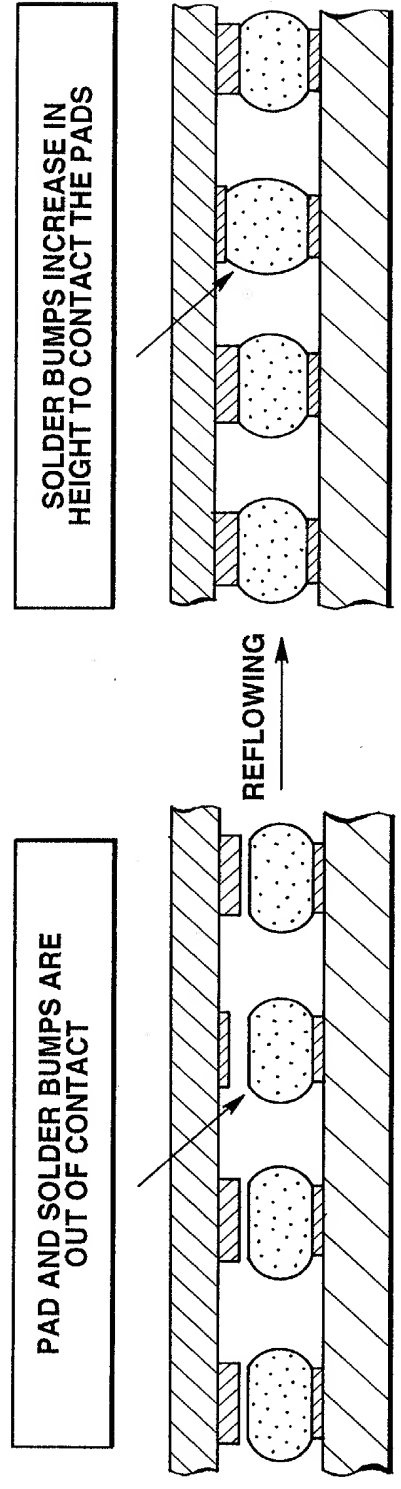


FIG.8

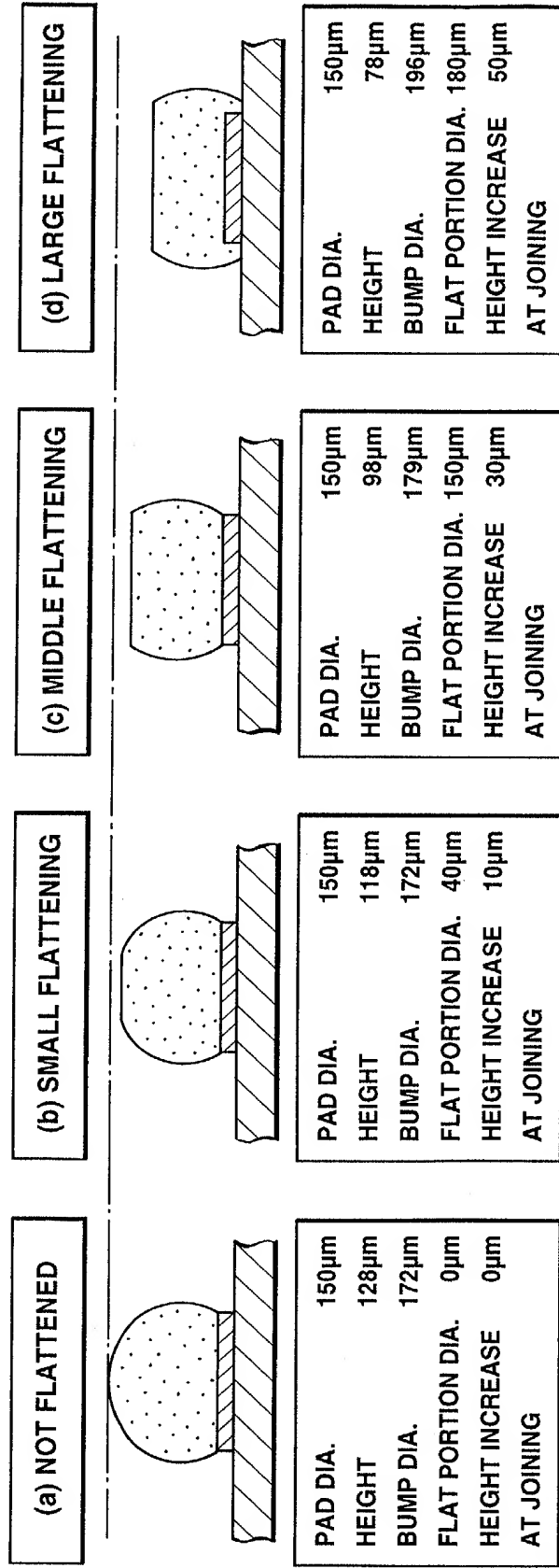


FIG.9

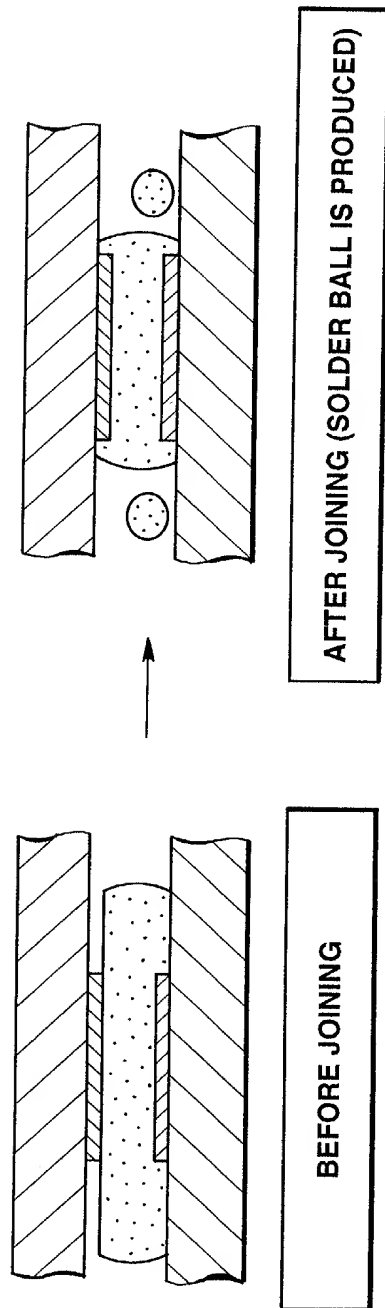
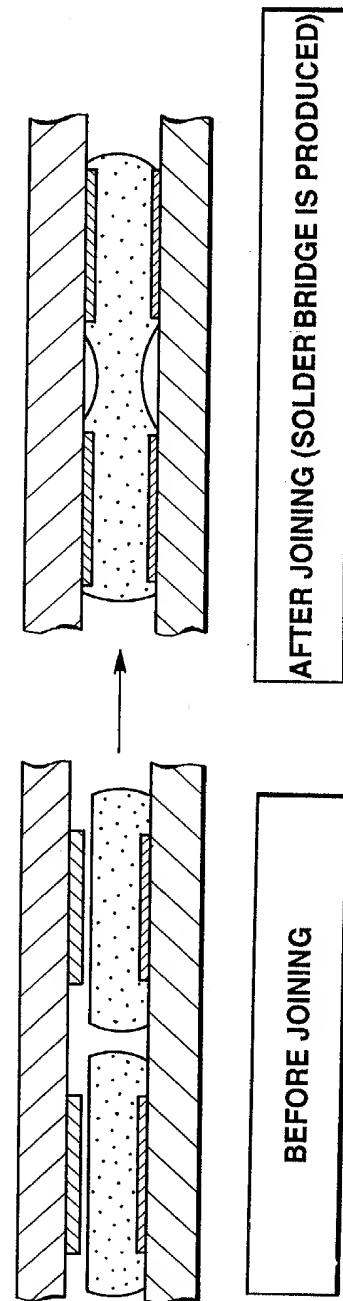


FIG.10

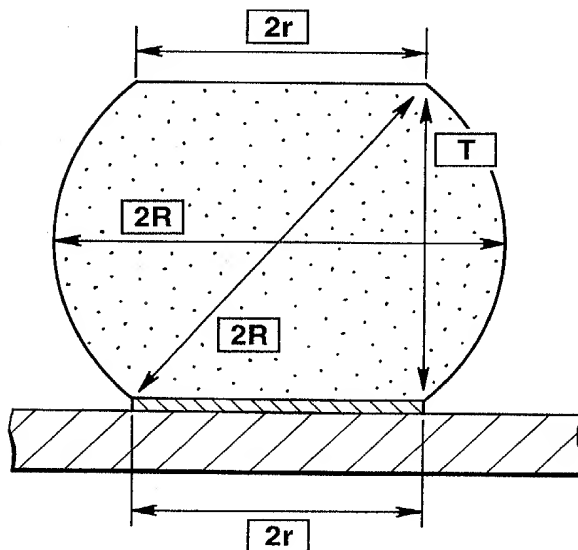




# FIG.11A

AT THE TIME OF  
FLATTENING  
OF SOLDER BUMP

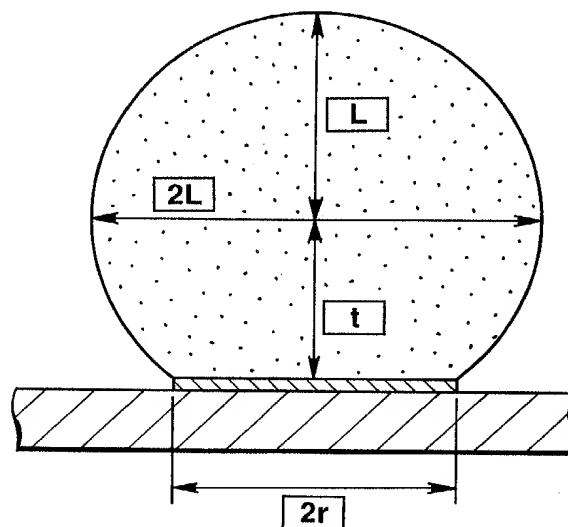
BUMP HEIGHT	$T$
FLAT PORTION DIA.	$2r$
BUMP DIA.	$2R$
PAD DIA.	$2r$
BUMP VOLUME	$S$



# FIG.11B

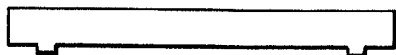
AT THE TIME OF  
REFLOWING  
OF SOLDER BUMP

BUMP HEIGHT	$L + t$
BUMP DIA.	$2L$
PAD DIA.	$2r$
BUMP VOLUME	$S$





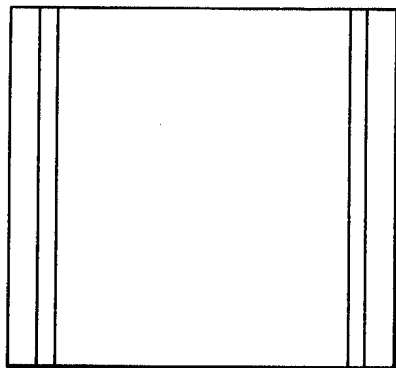
**FIG.13A**



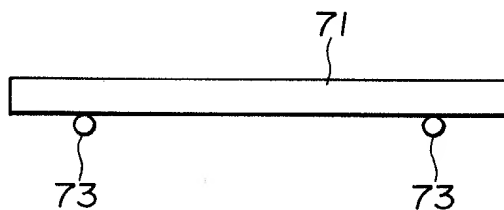
**FIG.13C**



**FIG.13B**



**FIG.14A**



**FIG.14B**

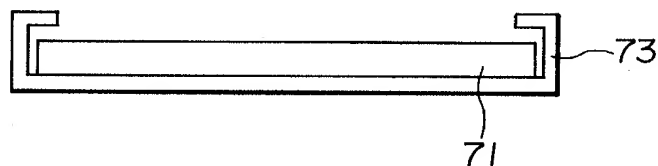


FIG.15A

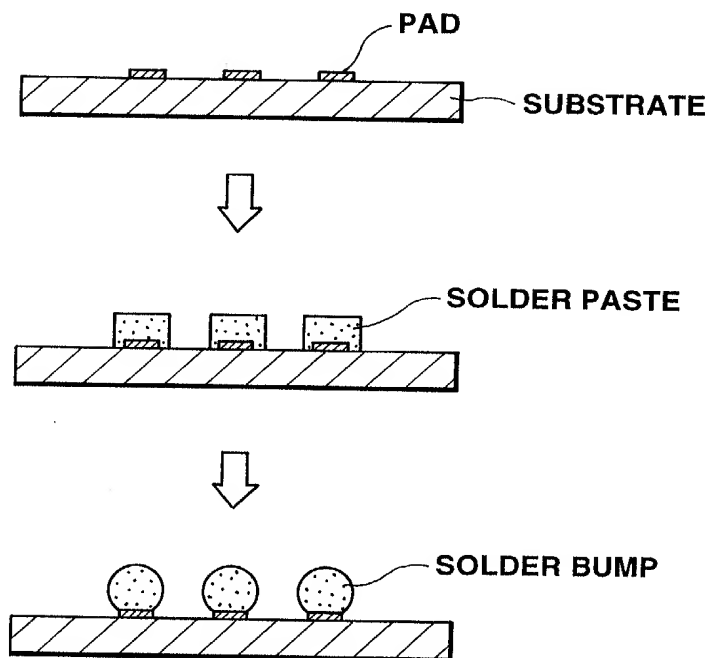


FIG.15B

